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(12) **United States Design Patent** (10) **Patent No.:** **US D793,400 S**
Lin et al. (45) **Date of Patent:** **** Aug. 1, 2017**

(54) **HEAT SINK FOR MEMORY MODULE**

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(57) **CLAIM**

(73) Assignee: **Kingston Digital, Inc.**, Fountain Valley, CA (US)

We claim the ornamental design for a heat sink for memory module, as shown and described.

(**) Term: **15 Years**

DESCRIPTION

(21) Appl. No.: **29/563,885**

(22) Filed: **May 9, 2016**

(51) **LOC (10) Cl.** **14-02**

(52) **U.S. Cl.**
USPC **D14/435; D14/436; D13/179**

(58) **Field of Classification Search**
USPC D14/435, 356, 242, 436, 433, 474, 240,
D14/496, 385, 358, 480.1–480.7;
360/97.01, 685, 686, 752, 737, 732, 784,
360/803; 439/345, 346, 377, 135, 144,
439/139–141, 147, 136, 638, 518, 131;
365/51, 63, 131; 710/52, 300, 313;
711/115, 103, 154, 161–162; 70/58;
323/210; 713/186, 1; 382/124; 235/492;
D13/179, 147; 165/80.1, 80.2, 80.3, 185;
361/715, 702, 710, 719, 717, 728, 730,
361/741, 709, 720, 704, 700, 752, 753,
361/701, 684, 711, 679.54, 690, 692;
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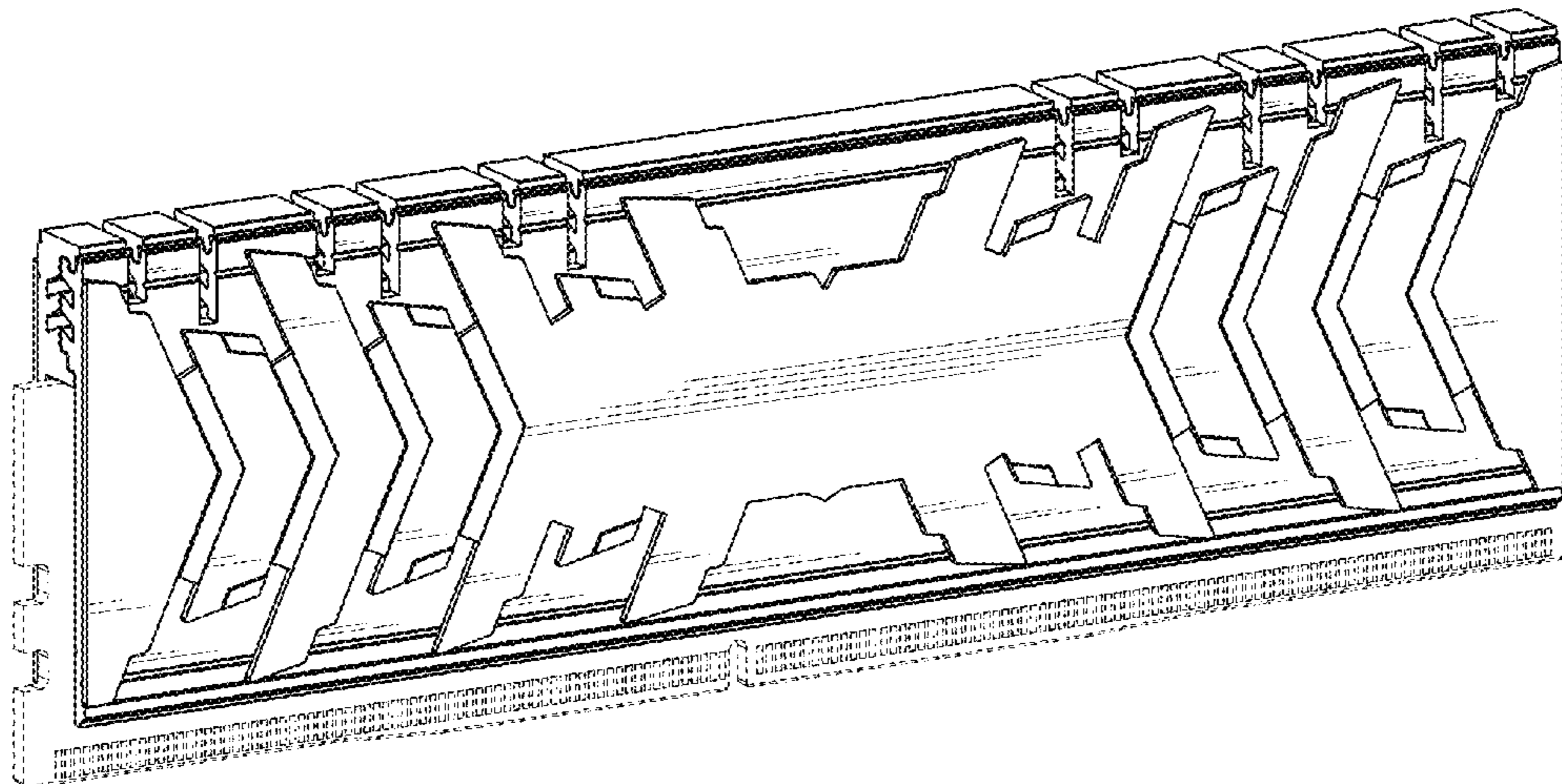
FIG. 1 is a perspective view of a heat sink for memory module showing the claimed design;
FIG. 2 is another perspective view thereof;
FIG. 3 is a front elevational view thereof;
FIG. 4 is a rear elevational view thereof;
FIG. 5 is a left side elevational view thereof;
FIG. 6 is a right side elevational view thereof;
FIG. 7 is a top plan view thereof;
FIG. 8 is a bottom plan view thereof;
FIG. 9 is an enlarged fragment view of the portion of the heat sink for memory module indicated by encircled region “A” of FIG. 2;
FIG. 10 is an enlarged fragment view of the portion of the heat sink for memory module indicated by encircled region “B” of FIG. 2;
FIG. 11 is an exemplary perspective view showing the heat sink for memory module in use; and,
FIG. 12 is another exemplary perspective view showing the heat sink for memory module in use.
The broken lines in FIG. 2 are employed merely to indicate which portions of the heat sink are shown in enlargement in FIGS. 9 and 10, and form no part of the claimed design.
The illustrative broken line showing of a card placed within the heat sink in FIGS. 11 and 12 depicts an exemplary component which might be used with the heat sink for memory module, and forms no part of the claimed design.

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1 Claim, 6 Drawing Sheets



(58) **Field of Classification Search**

USPC 257/707, 706, 708, 709, 719, 711-713,
 257/715, 718, E23.086, E23.103,
 257/E23.088, E23.098, E23.08, 4,
 257/E23.102, E23.101, E23.105, E25.023
 CPC G06K 19/06196; G06K 19/072; G06K
 19/0721-19/0728; G06K 19/073; G06K
 19/07309; G06K 19/077; G06K
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 19/07726; G06K 19/07728; G06K
 7/0021; G06K 7/0047; G06F
 21/77-21/80; G06F 21/85-21/88; G06F
 21/00; G06F 1/20; G06F 1/206; G06F
 1/185; G06Q 20/3229; G06Q 20/34;
 G06Q 20/341; G06Q 20/346; G06Q
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 G06Q 20/357; G06Q 20/3576; H05K
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 H05K 5/0269; H05K 5/0273; H05K
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 H05K 5/0291; H05K 5/0295; H05K 5/03;
 H05K 5/04; H05K 5/06; H05K
 5/061-5/069; H05K 7/00; H05K 7/005;
 H05K 7/02; H05K 7/023; H05K 7/026;
 H05K 7/20509; H05K 7/04; H05K 7/10;
 H05K 7/1418; H05K 7/142; H05K
 7/1405; H05K 7/1424; H05K
 7/1427-7/1439; H05K 7/1461; H05K
 7/1464-7/1474; H05K 7/1479; H05K
 7/1481; H05K 7/1485-7/1488; H05K
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 2201/098; H05K 2201/09818; H05K

2201/10; H05K 2201/10007; H04N
 2201/216; H01R 13/62933; H01R
 13/62905; H01R 13/6275; H01R 13/6395;
 H01R 13/62938; H01R 13/64; H01R
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 H01R 13/633; H01R 23/7005; H01R
 23/682; H01R 23/684; H01R 23/70;
 H01R 23/7068; H01R 23/7026; H01R
 31/065; H01R 27/02; H01R 2103/00;
 H01R 12/7029; H01R 12/83; G11C 5/04;
 H01L 23/4093; H01L 23/3672; H01L
 23/3675; H01L 23/373; H01L 23/4043;
 H01L 23/405; H01L 23/4062; H01L
 23/427; H01L 23/473; H01L 23/367;
 H01L 23/4006; H01L 23/552; H01L
 2924/00; H01L 2924/0002

See application file for complete search history.

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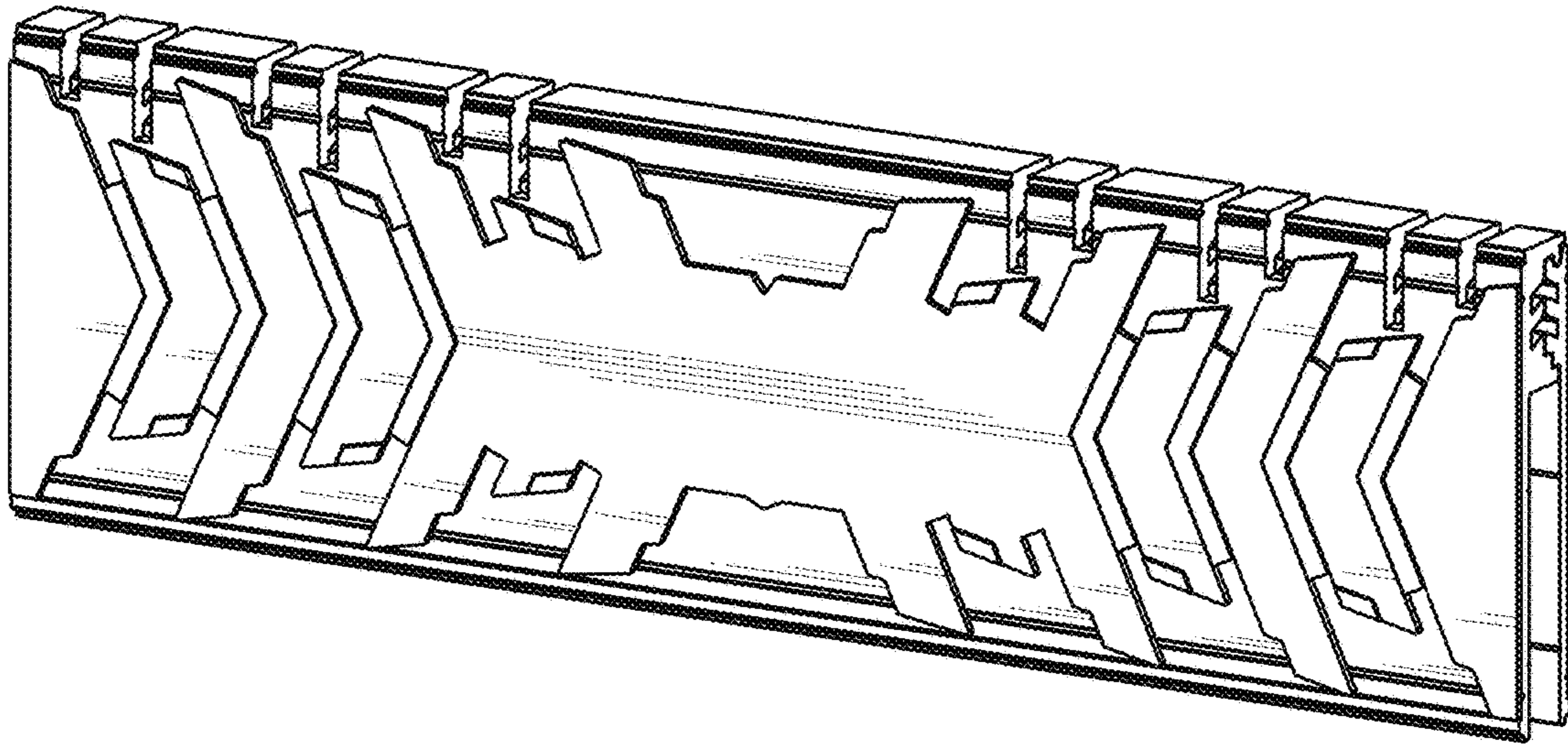


FIG. 1

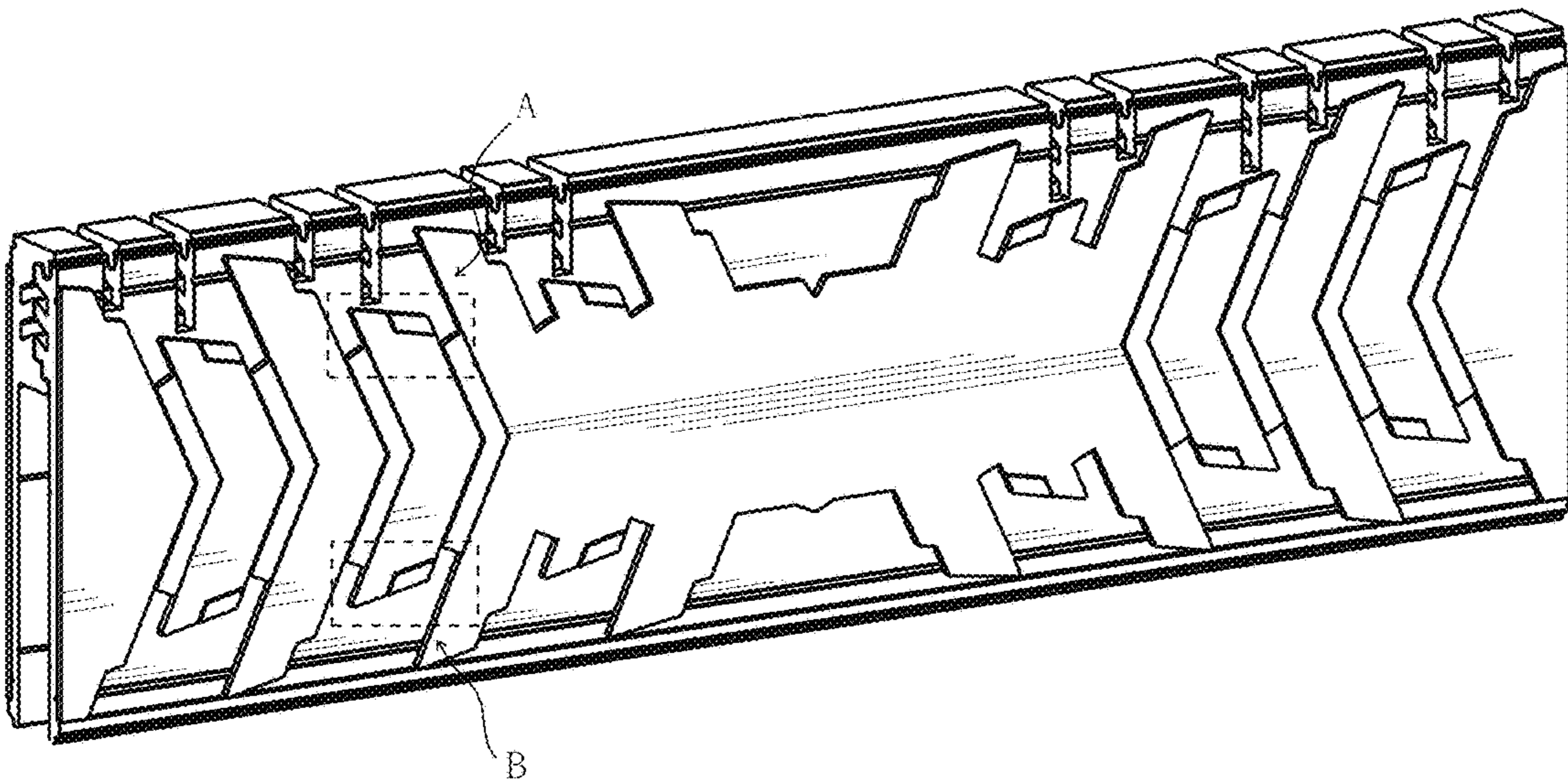


FIG. 2

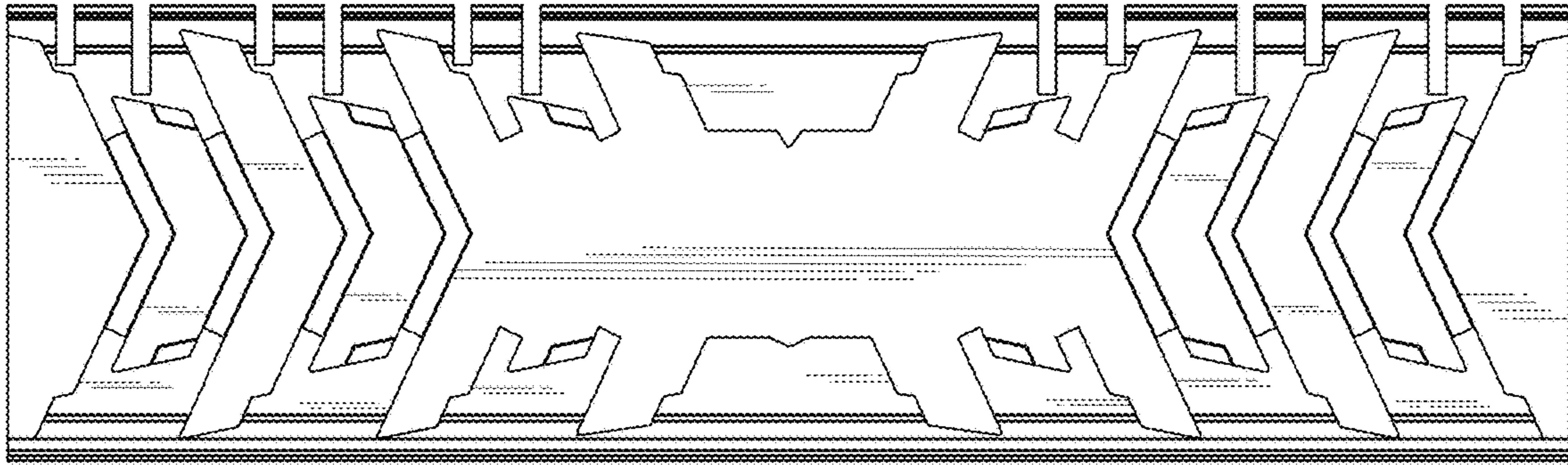


FIG.3

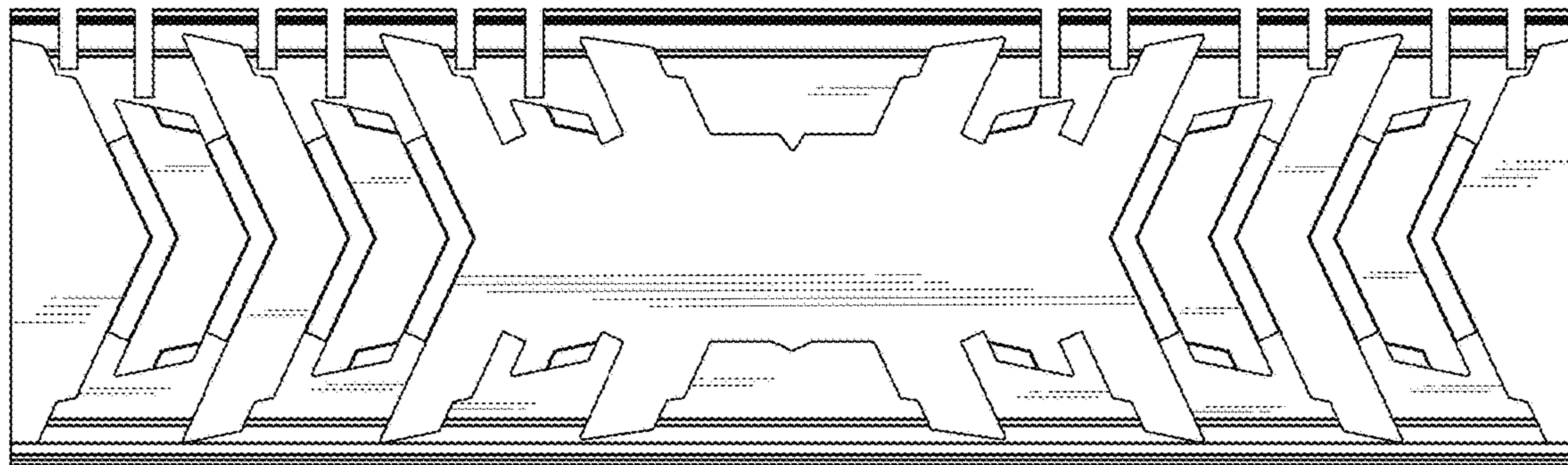


FIG.4

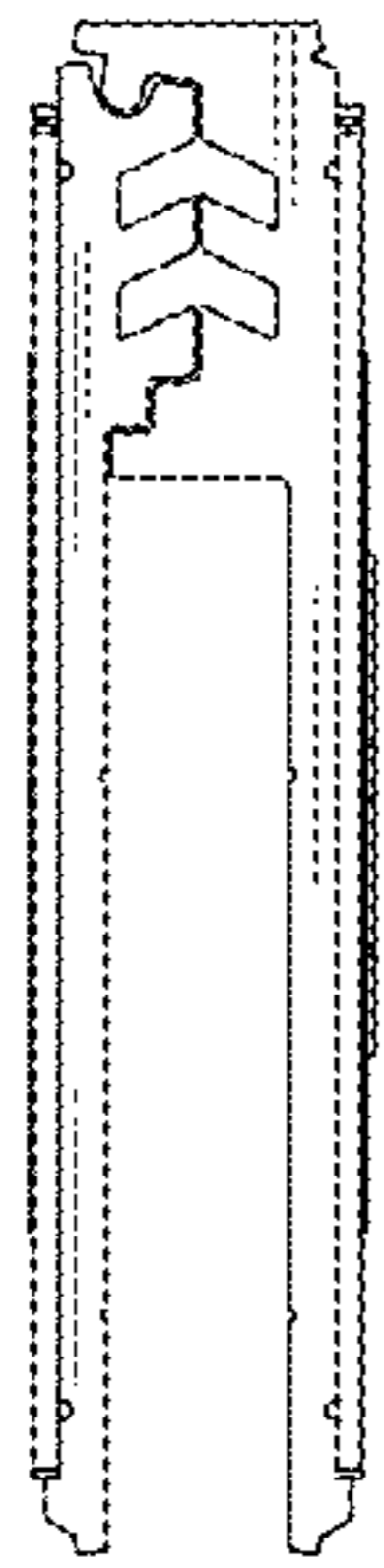


FIG. 5

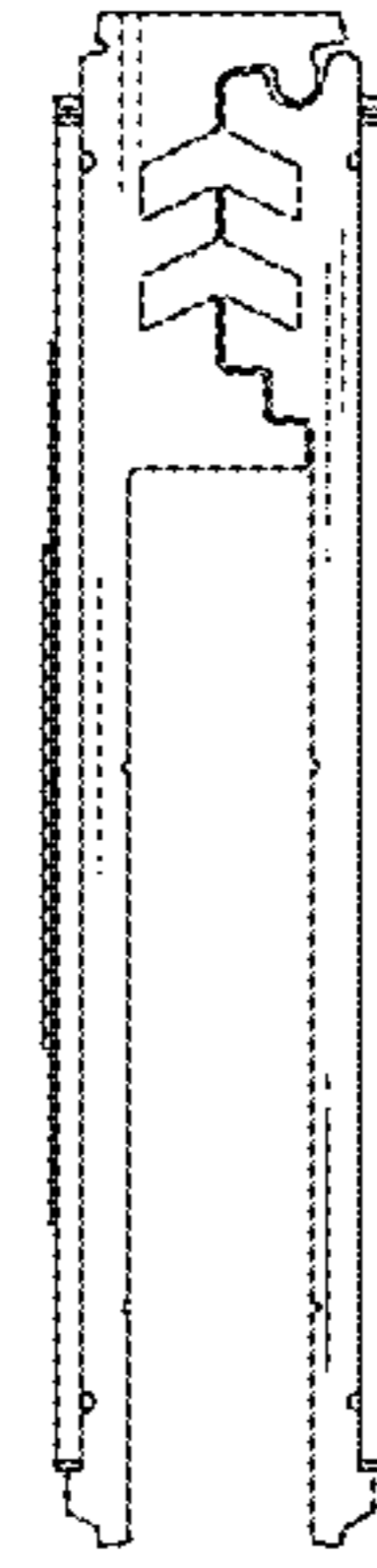


FIG. 6



FIG. 7



FIG. 8

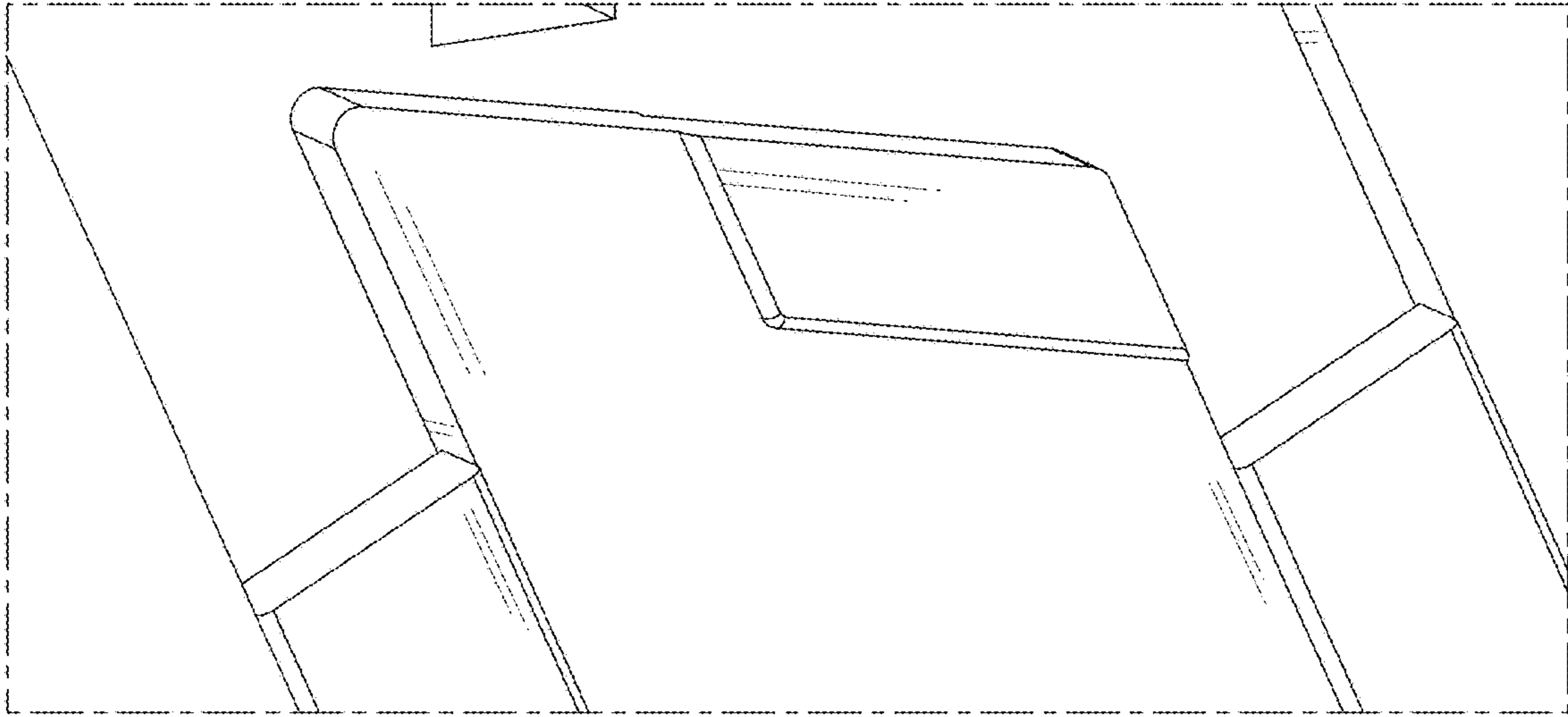


FIG. 9

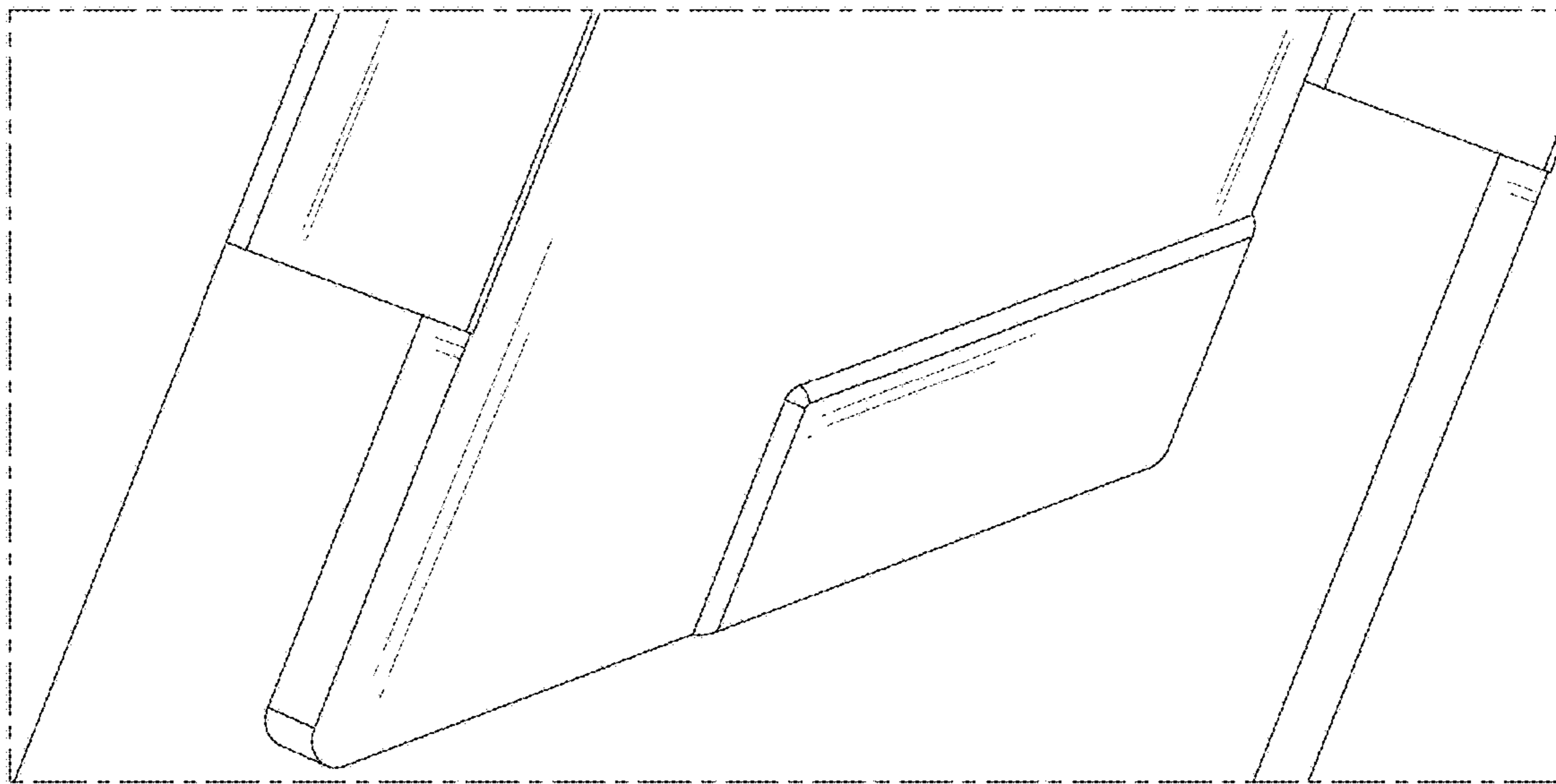


FIG. 10

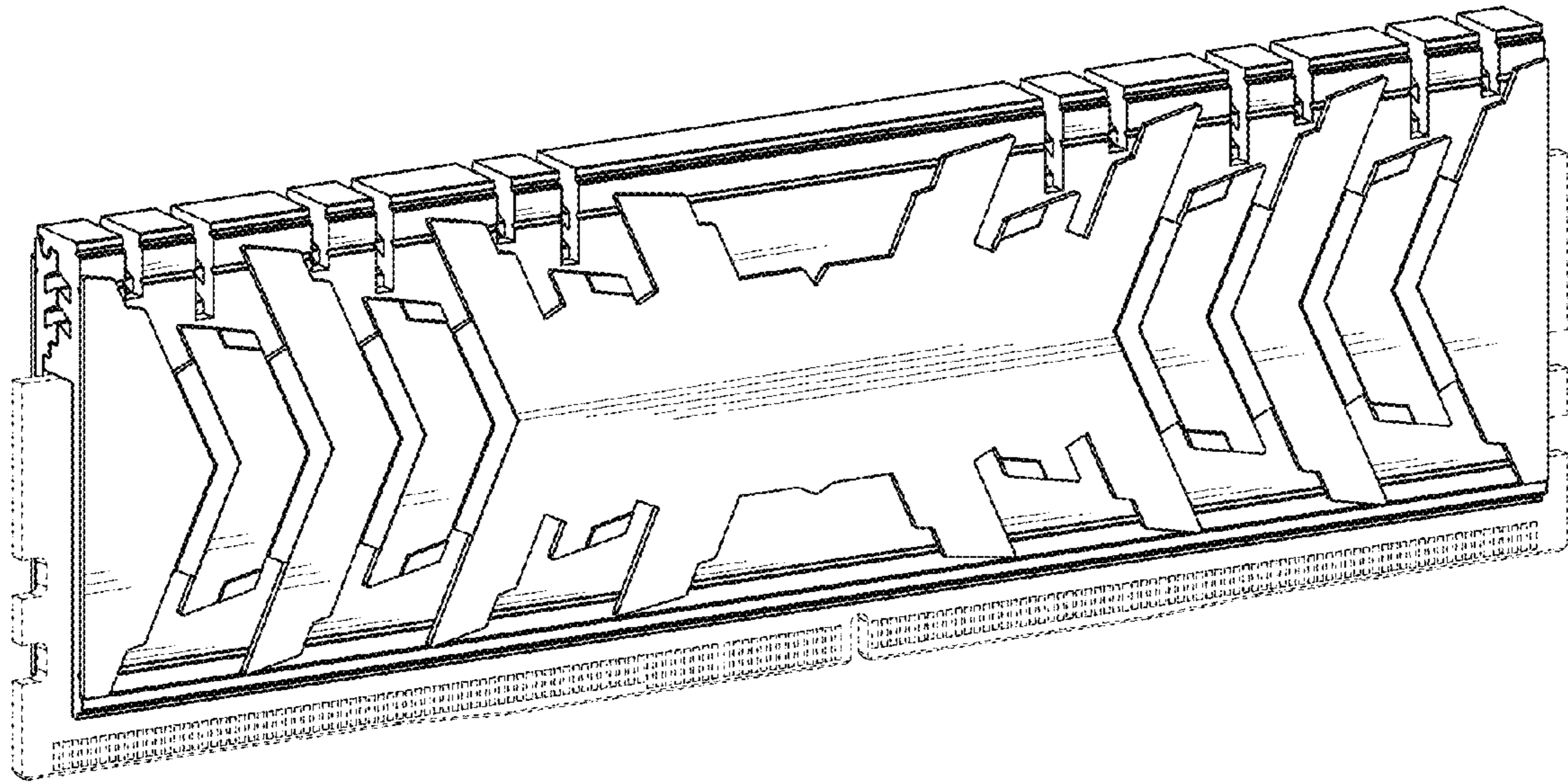


FIG. 11

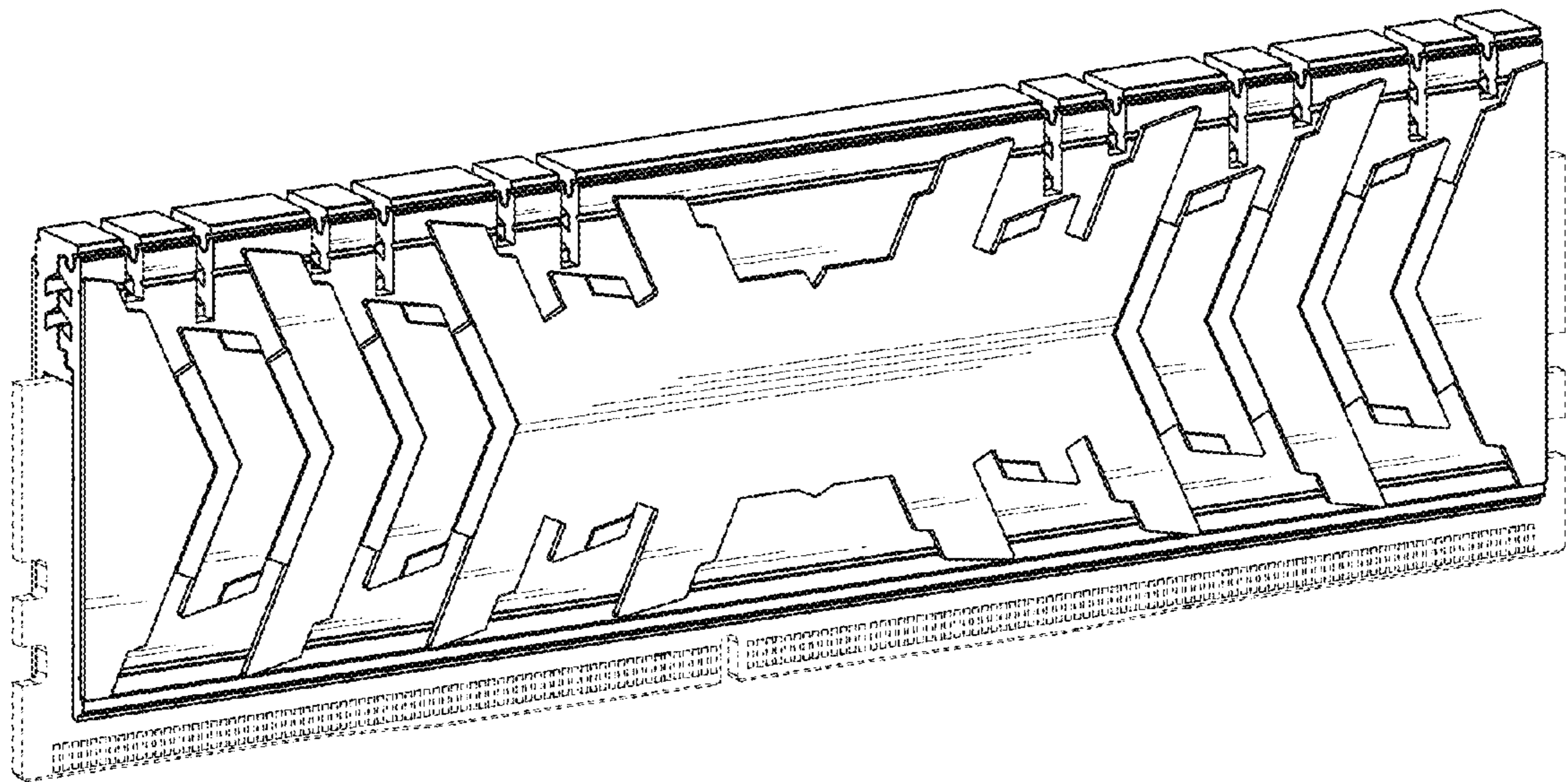


FIG. 12